Claim(s)

1. A holder for a module for connection to a circuit in electronic equipment, the holder being arranged to receive the electronic module and having a portion provided with at least one hole therethrough,

wherein the at least one hole is arranged to provide access through the holder to the circuit for testing.

2. The holder of claim 1 wherein the at least one hole is arranged to be covered by the electronic module when positioned in the holder.

3. The holder of claim 1 or 2 wherein the holder is provided with a plurality of holes therethrough.

4. The holder of claim 1, 2 or 3 wherein the holder is arranged to be mounted on the circuit by one of A-B:

A surface mount technology,

B plated through hole technology.

5. The holder of any preceding claim wherein the holder is further provided with a conductive layer on a surface for positioning adjacent the circuit.

6. The holder of any preceding claim wherein the module comprises a subscriber identification module.

7. The holder of any preceding claim wherein the electronic equipment comprises wireless communication equipment.

8. The holder of any preceding claim wherein the wireless communication equipment comprises a portable modem.

9. The holder of any preceding claim wherein the circuit is provided in a printed circuit board.

10. The holder of any preceding claim wherein the holder is of moulded plastics material.

11. A method of assembling a holder for a module on a circuit for electronic equipment, the method comprising:

providing a circuit;

providing a holder for a module for connection to the circuit, the holder being arranged to receive the electronic module and having a portion provided with at least one hole therethrough; and

mounting the holder on the circuit.

12. The method of claim 11 further comprising inserting the module in the holder such that the at least one hole is covered by the electronic module.

13. The method of claim 11 or 12 wherein the holder is provided with a plurality of holes therethrough.

14. The method of claim 11, 12 or 13 wherein the step of mounting comprises mounting the module on the circuit by one of A-B:

A surface mount technology,

B plated through hole technology.

15. The method of any one of claims 11-14 wherein the holder is further provided with a conductive layer on a surface positioned adjacent the circuit.

16. The method of any one of claims 11-15 wherein the module comprises a subscriber indentification module.

17. The method of any one of claims 11-16 wherein the electronic equipment comprises wireless communication equipment.

18. The method of any one of claims 11-17 wherein the wireless communication equipment comprises a portable modem.

19. The method of any one of claims 11-18 wherein the circuit is provided in a printed circuit board.

20. The method of any preceding claim wherein the holder is moulded of plastics material.

21 A method of testing comprising the method of assembling a holder for a module on a circuit for electronic equipment as claimed in any one of claims 11-20, and ; and testing the circuit through the at least one hole.

22. An electronic circuit having mounted thereon the holder of any one of claims 1-10.

23. A holder for a module for connection to a circuit in electronic equipment substantially as hereinbefore described with reference to the accompanying drawings.

24. A method of of assembling a holder for a module on a circuit for electronic equipment substantially as hereinbefore described with reference to the accompanying drawings.